

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

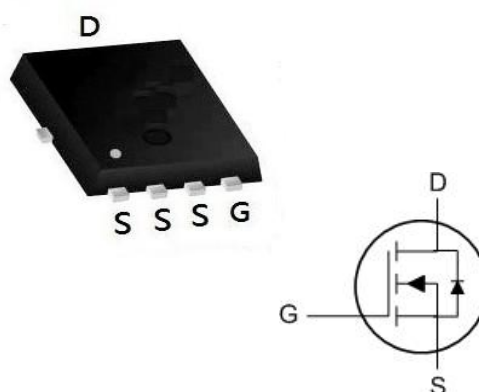
- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

Product Summary



| BVDSS | RDSON | ID |
|-------|-------|-----|
| 100V | 10mΩ | 40A |

PDFN3333-8L Pin Configuration



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

| Parameter | | Symbol | Value | Unit |
|--|---------------------------|----------------|------------|------------------|
| Drain-Source Voltage | | V_{DS} | 100 | V |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| Continuous Drain Current | $T_C = 25^\circ\text{C}$ | I_D | 40 | A |
| | $T_C = 100^\circ\text{C}$ | | 18.5 | |
| Pulsed Drain Current ¹ | | I_{DM} | 120 | A |
| Single Pulse Avalanche Energy ² | | E_{AS} | 80 | mJ |
| Total Power Dissipation | $T_C = 25^\circ\text{C}$ | P_D | 67.5 | W |
| Operating Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|--------------------|
| Thermal Resistance from Junction-to-Ambient ³ | $R_{\theta JA}$ | 45 | $^\circ\text{C/W}$ |
| Thermal Resistance from Junction-to-Lead | $R_{\theta JC}$ | 1.85 | $^\circ\text{C/W}$ |

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

| Parameter | | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---|----------------------|---------------|--|------|------|-----------|---------|
| Static Characteristics | | | | | | | |
| Drain-Source Breakdown Voltage | | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 100 | - | - | V |
| Gate-Body Leakage Current | | I_{GSS} | $V_{DS} = 0V, V_{GS} = \pm 20V$ | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | $T_J = 25^{\circ}C$ | I_{DSS} | $V_{DS} = 100V, V_{GS} = 0V$ | - | - | 1 | μA |
| | $T_J = 100^{\circ}C$ | | | - | - | 100 | |
| Gate-Threshold Voltage | | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1 | 1.7 | 2.5 | V |
| Drain-Source on-Resistance ⁴ | | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 20A$ | - | 10 | 12.5 | mΩ |
| | | | $V_{GS} = 4.5V, I_D = 10A$ | - | 12 | 16 | |
| Forward Transconductance ⁴ | | g_{fs} | $V_{DS} = 10V, I_D = 20A$ | - | 54 | - | S |
| Dynamic Characteristics ⁵ | | | | | | | |
| Input Capacitance | | C_{iss} | $V_{DS} = 50V, V_{GS} = 0V, f = 1MHz$ | - | 1208 | - | pF |
| Output Capacitance | | C_{oss} | | - | 144 | - | |
| Reverse Transfer Capacitance | | C_{rss} | | - | 11.3 | - | |
| Gate Resistance | | R_G | $f = 1MHz$ | - | 1.8 | - | Ω |
| Switching Characteristics ⁵ | | | | | | | |
| Total Gate Charge | | Q_g | $V_{GS} = 10V, V_{DS} = 50V, I_D = 20A$ | - | 22.7 | - | nC |
| Gate-Source Charge | | Q_{gs} | | - | 3 | - | |
| Gate-Drain Charge | | Q_{gd} | | - | 5 | - | |
| Turn-on Delay Time | | $t_{d(on)}$ | $V_{GS} = 10V, V_{DD} = 50V, R_G = 3\Omega, I_D = 20A$ | - | 9.2 | - | ns |
| Rise Time | | t_r | | - | 3.6 | - | |
| Turn-off Delay Time | | $t_{d(off)}$ | | - | 25.6 | - | |
| Fall Time | | t_f | | - | 4.4 | - | |
| Body Diode Reverse Recovery Time | | t_{rr} | $I_F = 20A, dI/dt = 100A/\mu s$ | - | 30 | - | ns |
| Body Diode Reverse Recovery Charge | | Q_{rr} | | - | 42 | - | nC |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Diode Forward Voltage ⁴ | | V_{SD} | $I_S = 20A, V_{GS} = 0V$ | - | - | 1.2 | V |
| Continuous Source Current | $T_C = 25^{\circ}C$ | I_S | - | - | - | 40 | A |

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.
2. The EAS data shows Max. rating . The test condition is $V_{DD} = 25V, V_{GS} = 10V, L = 0.4mH, I_{AS} = 20A$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test..

Typical Characteristics

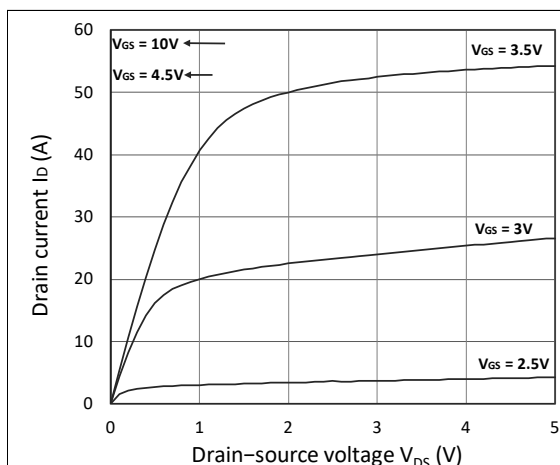


Figure 1. Output Characteristics

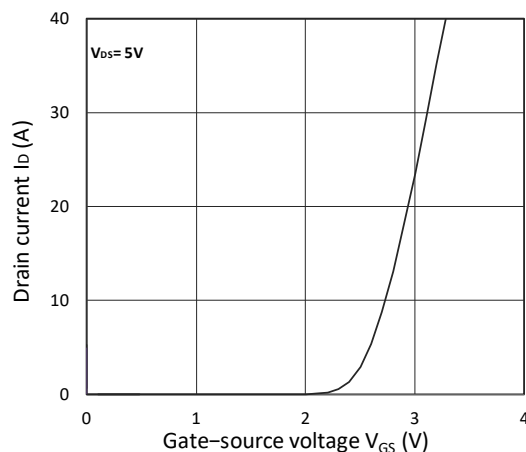


Figure 2. Transfer Characteristics

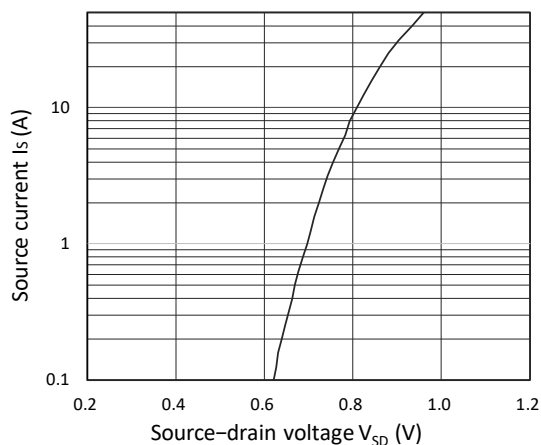


Figure 3. Forward Characteristics of Reverse

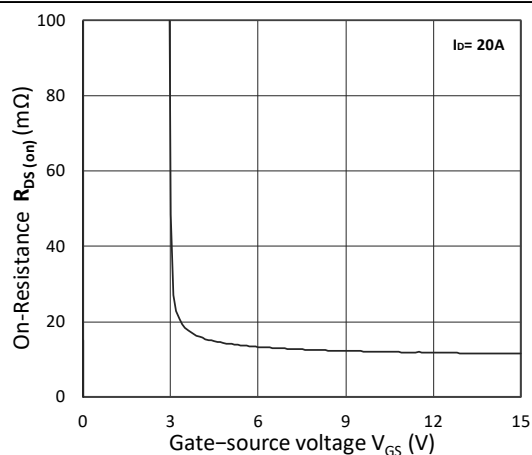


Figure 4. $R_{DS(on)}$ vs. V_{GS}

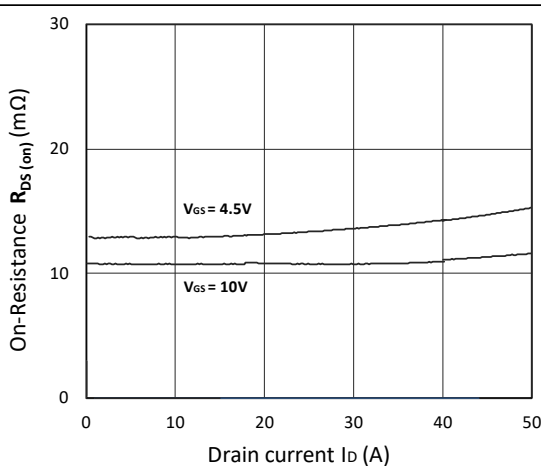


Figure 5. $R_{DS(on)}$ vs. I_D

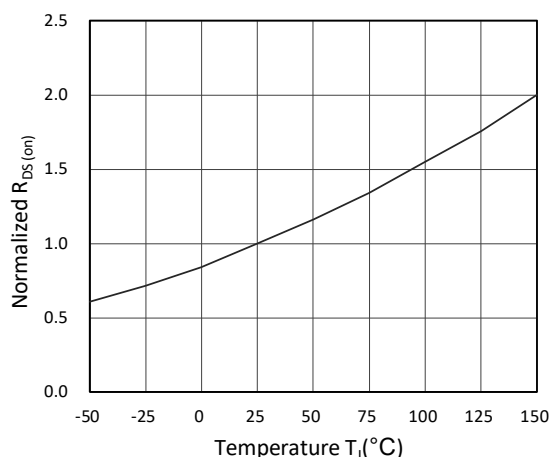


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

N-Ch 100V Fast Switching MOSFETs

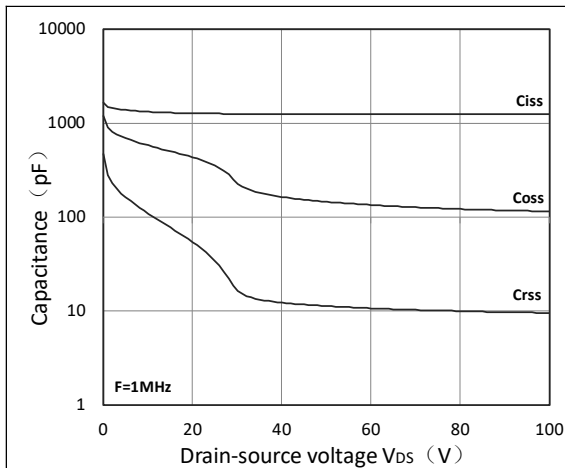


Figure 7. Capacitance Characteristics

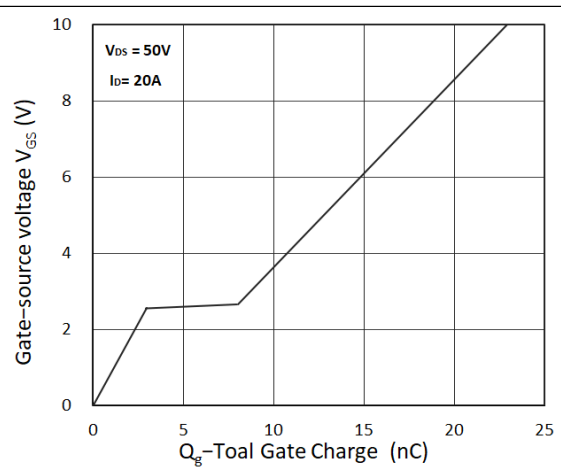


Figure 8. Gate Charge Characteristics

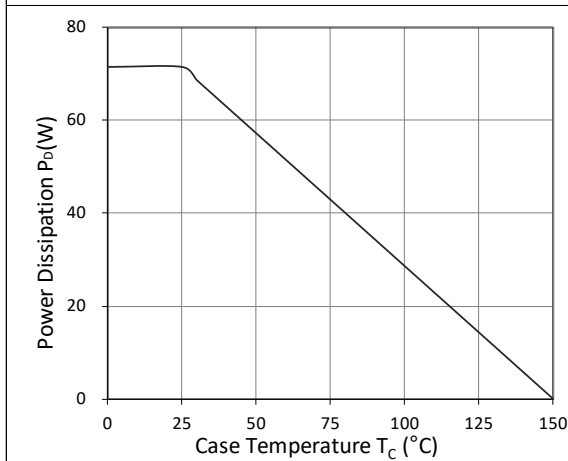


Figure 9. Power Dissipation

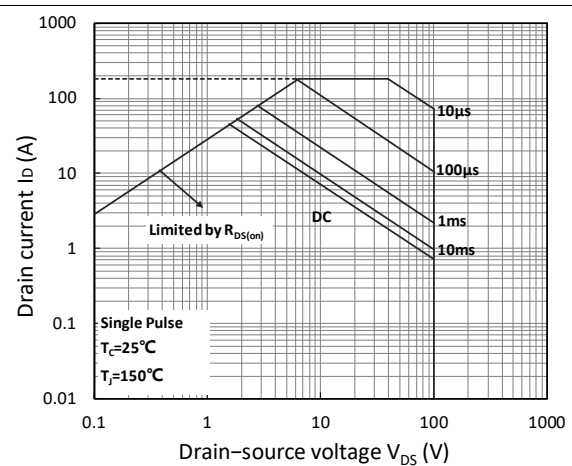


Figure 10. Safe Operating Area

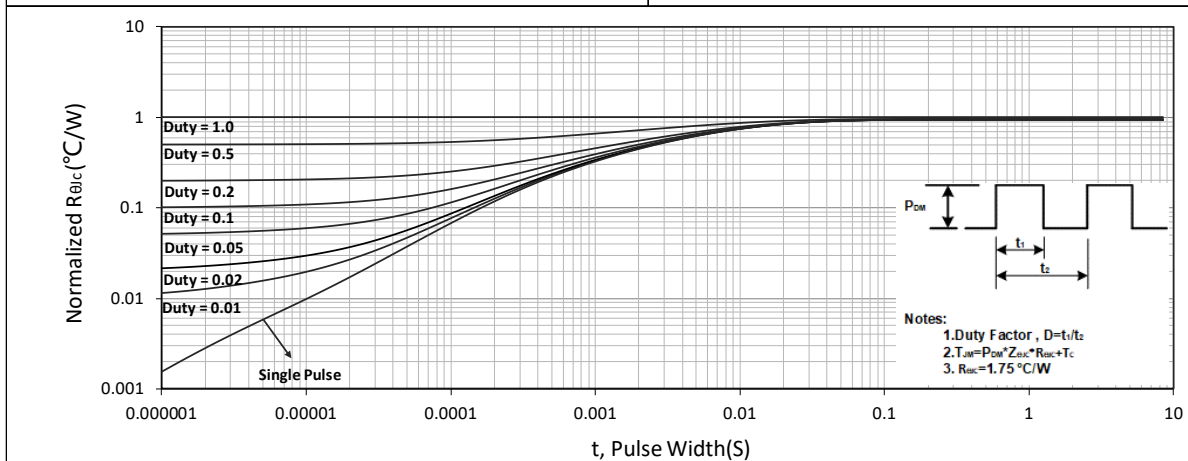


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

N-Ch 100V Fast Switching MOSFETs

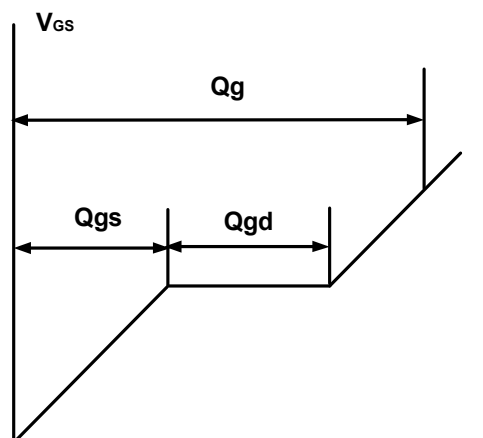
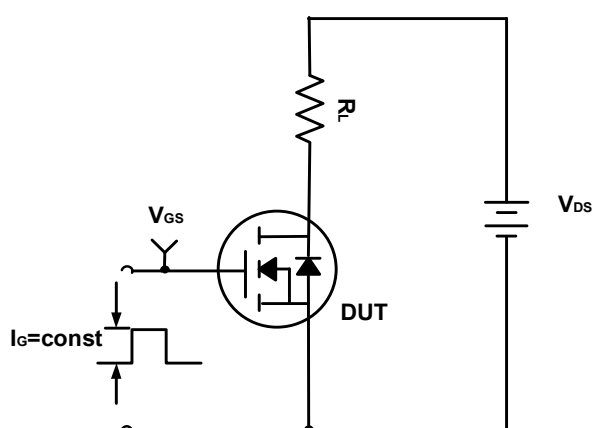


Figure A. Gate Charge Test Circuit & Waveforms

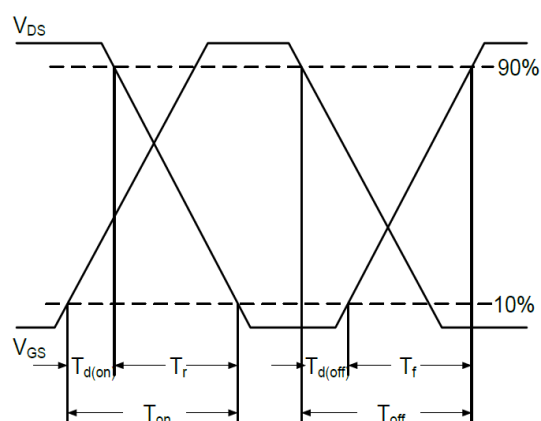
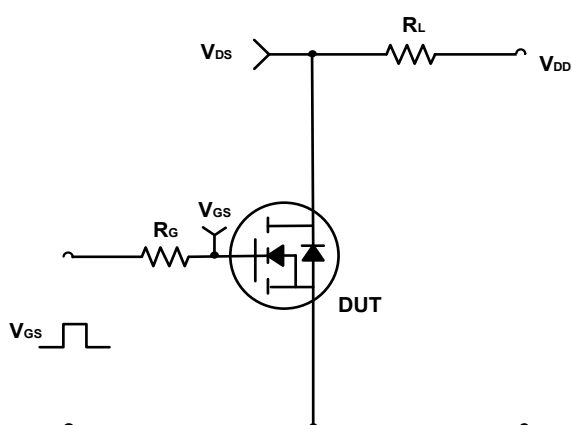


Figure B. Switching Test Circuit & Waveforms

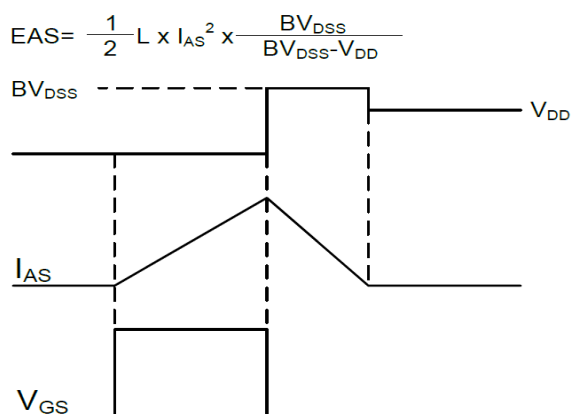
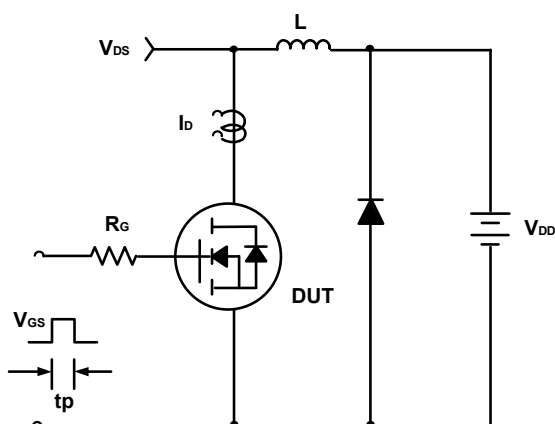
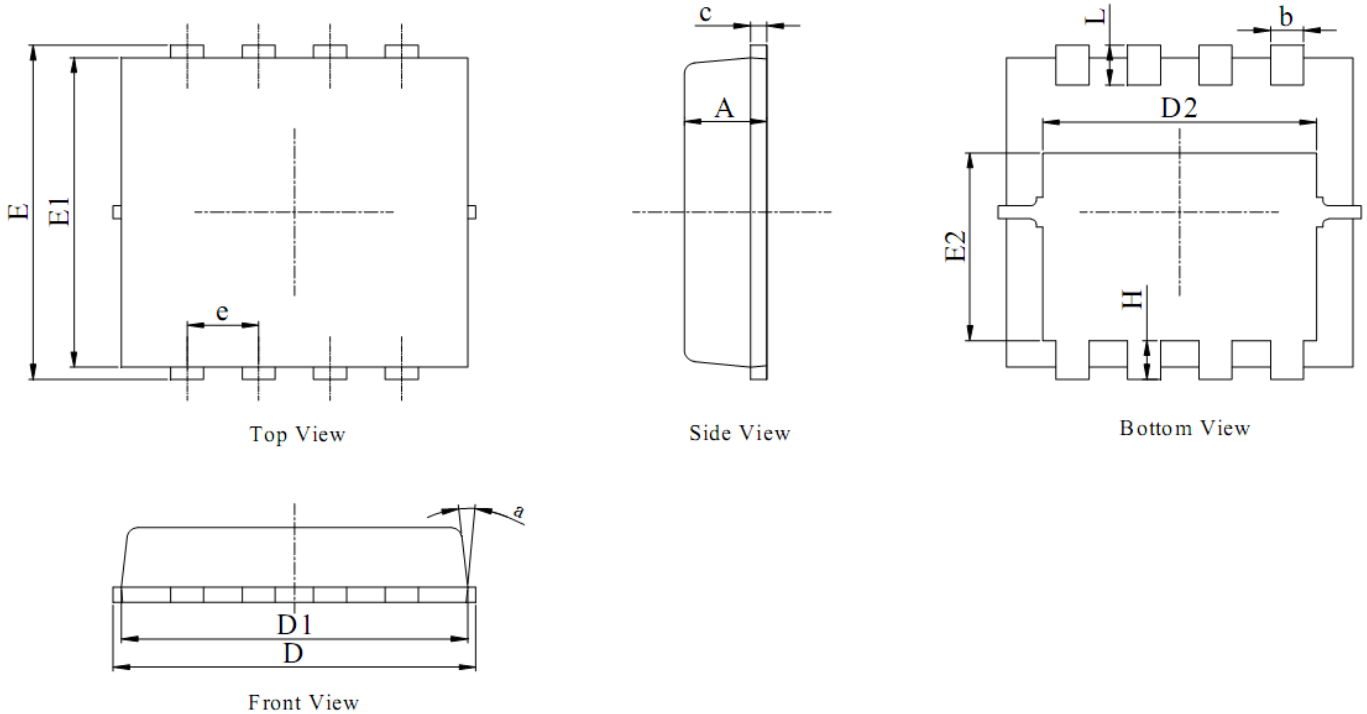


Figure C. Unclamped Inductive Switching Circuit & Waveforms

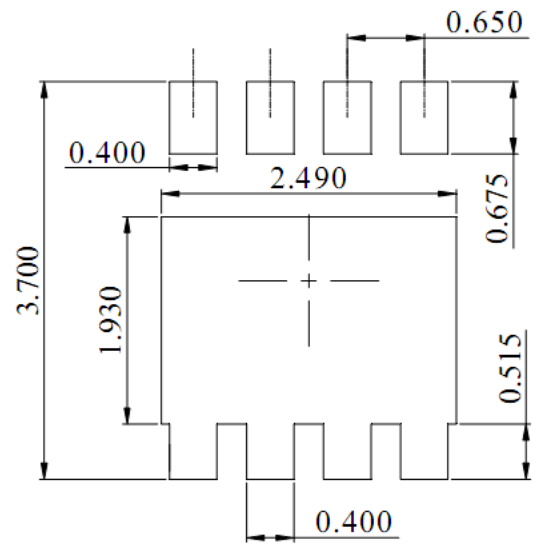
Package Mechanical Data-PDFN3333-8L-Single



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. ALL DIMENSIONS IN MILLIMETER (ANGLE IN DEGREE).
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

| DIM. | MILLIMETER | | |
|------|------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.70 | 0.75 | 0.80 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.10 | 0.20 | 0.25 |
| D | 3.00 | 3.15 | 3.25 |
| D1 | 2.95 | 3.05 | 3.15 |
| D2 | 2.39 | 2.49 | 2.59 |
| E | 3.20 | 3.30 | 3.40 |
| E1 | 2.95 | 3.05 | 3.15 |
| E2 | 1.70 | 1.80 | 1.90 |
| e | 0.65 BSC | | |
| H | 0.30 | 0.40 | 0.50 |
| L | 0.25 | 0.40 | 0.50 |
| a | --- | --- | 15° |



DIMENSIONS:MILLIMETERS